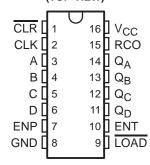
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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 9.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

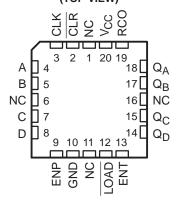
description/ordering information

The 'LV161A devices are 4-bit synchronous binary counters designed for 2-V to 5.5-V $V_{\rm CC}$ operation.

SN54LV161A . . . J OR W PACKAGE SN74LV161A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV161A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 D	Tube of 40	SN74LV161AD	11/404 A
	SOIC – D	Reel of 2500	SN74LV161ADR	LV161A
	SOP – NS	Reel of 2000	SN74LV161ANSR	74LV161A
4000 to 0500	SSOP – DB	Reel of 2000	SN74LV161ADBR	LV161A
-40°C to 85°C		Tube of 90 SN74LV161APW		
	TSSOP - PW	Reel of 2000	SN74LV161APWR	LV161A
		Reel of 250	SN74LV161APWT	
	TVSOP - DGV	Reel of 2000	SN74LV161ADGVR	LV161A
	CDIP – J	Tube of 25	SNJ54LV161AJ	SNJ54LV161AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV161AW	SNJ54LV161AW
	LCCC – FK	Tube of 55	SNJ54LV161AFK	SNJ54LV161AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that normally are associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the 'LV161A devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{\text{LOAD}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

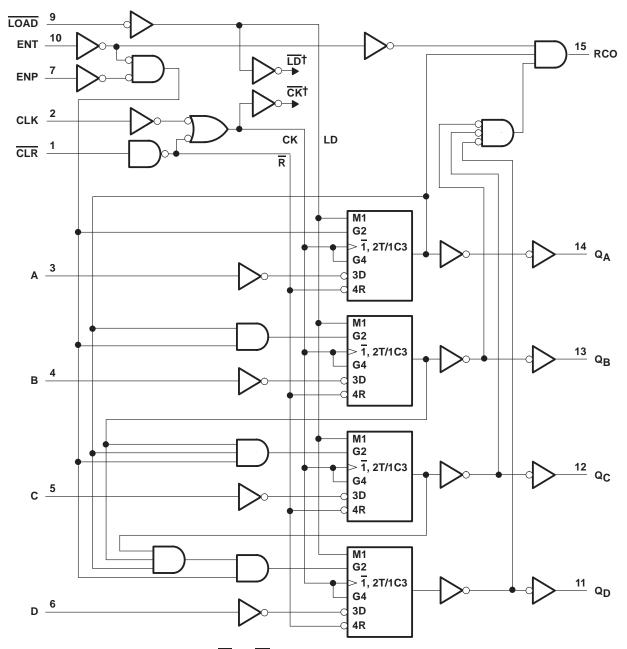
These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

	II	NPUTS				OUTI	PUTS			
CLR	LOAD	ENP	ENT	CLK	QA	QB	QC	QD	FUNCTION	
L	Х	Х	Χ	Х	L	L	L	L	Reset to "0"	
Н	L	X	Χ	\uparrow	A B C D Preset D				Preset Data	
Н	Н	X	L	\uparrow		No Change No				
Н	Н	L	Χ	\uparrow		No Change No C				
Н	Н	Н	Н	\uparrow		Count up Count				
Н	X	X	Χ	\uparrow		No CI	hange		No Count	



logic diagram (positive logic)

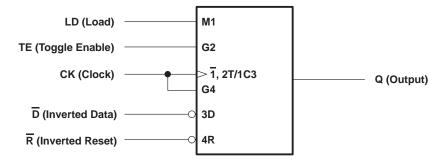


[†] For simplicity, routing of complementary signals \overline{LD} and \overline{CK} is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

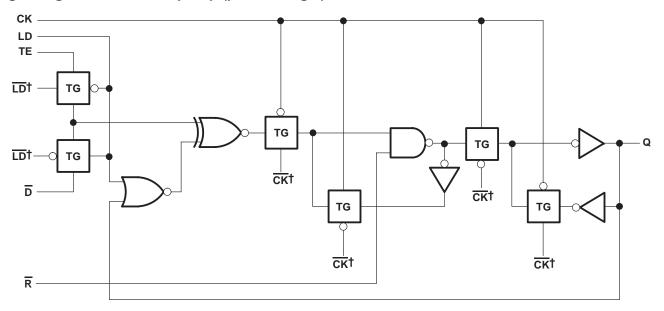
Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

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logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)

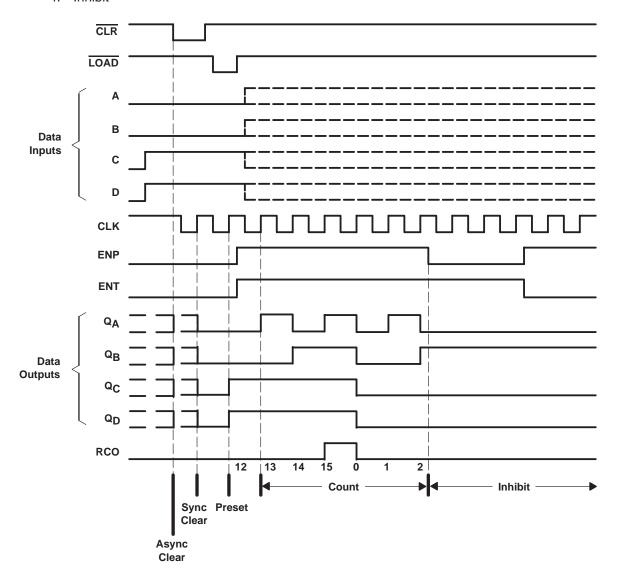


 $^{^{\}dagger}$ The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the overall logic diagram of the device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		
Output voltage range applied in high or low stat	te, VO (see Notes 1 and 2) .	\dots -0.5 V to V _{CC} + 0.5 V
Voltage range applied to any output in the power	er-off state, V _O (see Note 1)	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0)		–20 mA
Output clamp current, IOK (VO < 0)		–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 3):	D package	73°C/W
	DB package	82°C/W
	DGV package	120°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			SN54LV	161A	SN74L	/161A	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
	High level innerticate as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		$V_{CC} \times 0.7$		V
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
.,	Lauran lauran liana atau antan an	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V	CC×0.3	V	CC×0.3	V
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V	V	CC×0.3	V	CC×0.3	V
		V _{CC} = 4.5 V to 5.5 V	V	CC × 0.3	V	CC×0.3	
٧ı	Input voltage		00	5.5	0	5.5	V
Vo	Output voltage		0	Vcc	0	VCC	V
		V _{CC} = 2 V	Q.	-50		-50	μΑ
	Library and and an extension and	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V		-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		$V_{CC} = 2 V$		50		50	μΑ
1	Laveland autout annuart	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		V _{CC} = 4.5 V to 5.5 V		12		12	
		V _{CC} = 2.3 V to 2.7 V	0	200	0	200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$	0	100	0	100	ns/V
		V _{CC} = 4.5 V to 5.5 V	0	20	0	20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		1	SN54LV161A	SN74LV161A	
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX	MIN TYP MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1	V _{CC} -0.1	
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V
	I _{OH} = -12 mA	4.5 V	3.8	3.8	
	I _{OL} = 50 μA	2 V to 5.5 V	0.1	0.1	
	I _{OL} = 2 mA	2.3 V	0.4	0.4	V
VOL	I _{OL} = 6 mA	3 V	0.44	0.44	V
	I _{OL} = 12 mA	4.5 V	0.55	0.55	
lį	V _I = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0	5	5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V	1.8	1.8	pF

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timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			T _A = 1	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLK high or low	7		7		7		
t _W	Pulse duration	CLR low	7		7	4	7		ns
		CLR	4.5		4.5	15.11	4.5		
	0	Data (A, B, C, and D)	7.5		8.5	71.	8.5		
tsu	Setup time before CLK↑	ENP, ENT	9.5		11		11		ns
		LOAD low	10		11.5		11.5		
t _h	Hold time, all synchronous inputs after CLK↑		1.5		1.5		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
_	Dulas direction	CLK high or low	5		5		5		
t _w	Pulse duration	CLR low	5		5	4	5		ns
		CLR	2.5		2.5	15.71	2.5		
١.	0	Data (A, B, C, and D)	5.5		6.5	71.	6.5		
tsu	Setup time before CLK↑	ENP, ENT	7.5		9		9		ns
		LOAD low	8		9.5		9.5		
t _h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L	V161A	SN74L\	/161A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLK high or low	5		5		5		
t _w	Pulse duration	CLR low	5		5	4	5		ns
		CLR	1.5		1.5	10.71	1.5		
١.	0	Data (A, B, C, and D)	4.5		4.5	71.	4.5		
t _{su}	Setup time before CLK↑	ENP, ENT	5		6		6		ns
		LOAD low	5		6		6		
t _h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

242445752	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L\	/161A	SN74L	V161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			C _L = 15 pF	50*	125*		40*		40		MHz
fmax			C _L = 50 pF	30	95		25		25		IVII IZ
		Q			7.9*	16.2*	1*	19.5*	1	19.5	
	CLK	RCO (count mode)			8.9*	17*	1*	20.5*	1	20.5	
^t pd		RCO (preset mode)	C _L = 15 pF		11.9*	20.6*	1*	24.5*	1	24.5	ns
	ENT	RCO			8.3*	15.7*	1*	19*	1	19	
		Q			8.8*	17*	1* 4	20.5*	1	20.5	
^t PHL	CLR	RCO			9.8*	16.6*	1*	20*	1	20	
		Q			10.5	19.2	01	22.5	1	22.5	
	CLK	RCO (count mode)			11.7	20	1	23.5	1	23.5	
^t pd		RCO (preset mode)	C _L = 50 pF		14.5	23.6	1	27.5	1	27.5	ns
	ENT	RCO			11	18.7	1	22	1	22	
	CLD	Q			11.4	20	1	23.5	1	23.5	
^t PHL	CLR	RCO			12.6	19.6	1	23	1	23	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	4 = 25°C	;	SN54L	V161A	SN74L	/161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f			C _L = 15 pF*	80*	165*		70*		70		MHz
f _{max}			C _L = 50 pF	55	125		50		50		IVITZ
		Q			6	12.8	1*	15*	1	15	
	CLK	RCO (count mode)			6.7	13.6	1*	16*	1	16	
^t pd*		RCO (preset mode)	C _L = 15 pF		8.6	17.2	1*	20*	1	20	ns
	ENT	RCO			6.2	12.3	1*	14.5*	1	14.5	
		Q			6.5	13.6	1*,4	16*	1	16	
^t PHL*	CLR	RCO			7.2	13.2	1*	15.5*	1	15.5	
		Q			7.8	16.3	01	18.5	1	18.5	
	CLK	RCO (count mode)			8.7	17.1	1	19.5	1	19.5	
^t pd		RCO (preset mode)	C _L = 50 pF		10.6	20.7	1	23.5	1	23.5	ns
	ENT	RCO			8.3	15.8	1	18	1	18	
4	CLD	Q			8.4	17.1	1	19.5	1	19.5	
^t PHL	CLR	RCO			9.2	16.7	1	19	1	19	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L\	/161A	SN74L	V161A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
£			C _L = 15 pF	135*	220		115*		115		MHz
fmax			C _L = 50 pF	95	165		85		85		IVITIZ
		Q			4.5*	8.1*	1*	9.5*	1	9.5	
	CLK	RCO (count mode)			5.1*	8.1*	1*	9.5*	1	9.5	
^t pd		RCO (preset mode)	C _L = 15 pF		6.3*	10.3*	1*	12*	1	12	ns
	ENT	RCO			4.8*	8.1*	1*	9.5*	1	9.5	
		Q			4.9*	9*	1*,<	10.5*	1	10.5	
^t PHL	CLR	RCO			5.5*	8.6*		10*	1	10	
		Q			5.9	10.1	O ¹	11.5	1	11.5	
	CLK	RCO (count mode)			6.6	10.1	1	11.5	1	11.5	
^t pd		RCO (preset mode)	C _L = 50 pF		7.8	12.3	1	14	1	14	ns
	ENT	RCO			6.1	10.1	1	11.5	1	11.5	
4	CLR	Q			6.3	11	1	12.5	1	12.5	
^t PHL	CLK	RCO]		6.9	10.6	1	12	1	12	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

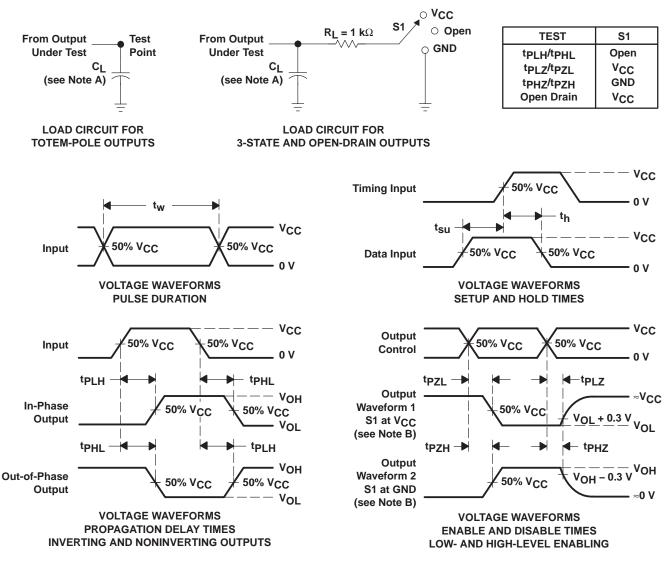
	DADAMETED	SN	74LV161	Α	
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3	0.8	V
V _{OL} (V)	Quiet output, minimum dynamic VOL		-0.2	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
C _{pd}	Power dissipation capacitance	C. FO.D. 6 40 MU	3.3 V	23.6	pF
		$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	25.8	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV161AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161ANSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV161A	Samples
SN74LV161APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples
SN74LV161APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

10-Jun-2014

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. **Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight

- in homogeneous material)
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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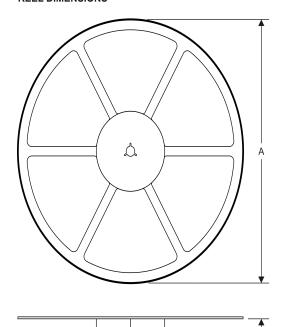
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PACKAGE MATERIALS INFORMATION

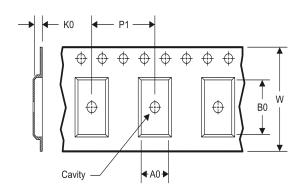
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV161ADBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV161ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV161ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV161ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV161APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV161APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV161ADBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74LV161ADGVR	TVSOP	DGV	16	2000	367.0	367.0	35.0
SN74LV161ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV161ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LV161APWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV161APWT	TSSOP	PW	16	250	367.0	367.0	35.0

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

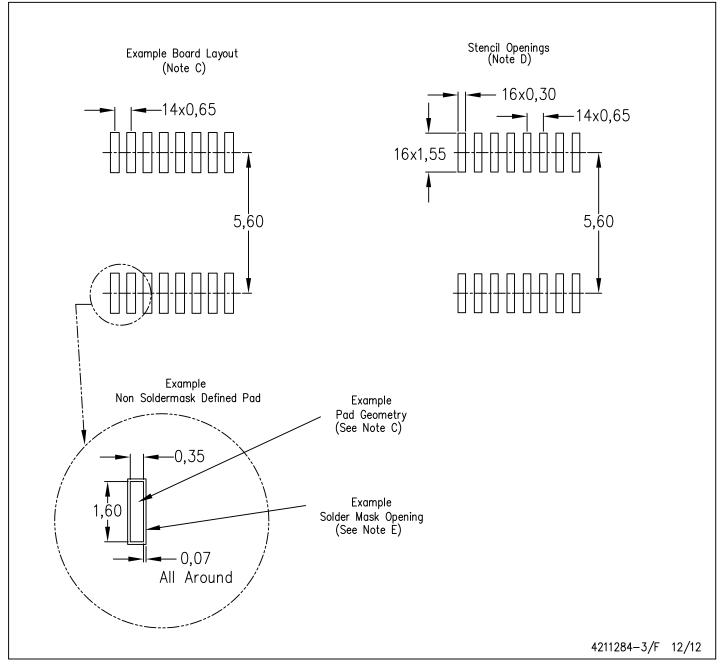


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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